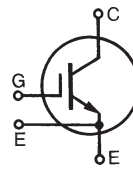


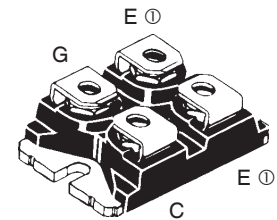
Medium-Speed Low-Vsat PT IGBT for 5-40 kHz Switching



$V_{CES} = 600V$
 $I_{C25} = 430A$
 $V_{CE(sat)} \leq 1.50V$

Symbol	Test Conditions	Maximum Ratings	
V_{CES}	$T_J = 25^\circ C$ to $150^\circ C$	600	V
V_{CGR}	$T_J = 25^\circ C$ to $150^\circ C$, $R_{GE} = 1M\Omega$	600	V
V_{GES}	Continuous	± 20	V
V_{GEM}	Transient	± 30	V
I_{C25}	$T_C = 25^\circ C$ (Chip Capability)	430	A
I_{C110}	$T_C = 110^\circ C$	200	A
I_{LRMS}	Terminal Current Limit	200	A
I_{CM}	$T_C = 25^\circ C$, 1ms	1500	A
SSOA	$V_{GE} = 15V$, $T_{VJ} = 125^\circ C$, $R_G = 1\Omega$	$I_{CM} = 400$	A
(RBSOA)	Clamped Inductive Load	@ $V_{CE} \leq V_{CES}$	V
P_C	$T_C = 25^\circ C$	1000	W
T_J		-55 ... +150	$^\circ C$
T_{JM}		150	$^\circ C$
T_{stg}		-55 ... +150	$^\circ C$
V_{ISOL}	50/60Hz	t = 1min	2500 V~
	$I_{ISOL} \leq 1mA$	t = 1s	3000 V~
M_d	Mounting Torque	1.5/13	Nm/lb.in
	Terminal Connection Torque (M4)	1.3/11.5	Nm/lb.in
Weight		30	g

SOT-227B, miniBLOC
 E153432



G = Gate, C = Collector, E = Emitter
 ① either emitter terminal can be used as Main or Kelvin Emitter

Features

- Optimized for Low Conduction and Switching Losses
- Square RBSOA
- High Current Capability
- Isolation Voltage 3000 V~
- International Standard Package

Advantages

- High Power Density
- Low Gate Drive Requirement

Applications

- Power Inverters
- UPS
- Motor Drives
- SMPS
- PFC Circuits
- Battery Chargers
- Welding Machines
- Lamp Ballasts

Symbol	Test Conditions ($T_J = 25^\circ C$, Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
BV_{CES}	$I_C = 1mA$, $V_{GE} = 0V$	600		V
$V_{GE(th)}$	$I_C = 8mA$, $V_{CE} = V_{GE}$	3.0		5.0 V
I_{CES}	$V_{CE} = V_{CES}$, $V_{GE} = 0V$ $T_J = 125^\circ C$			100 μA
				4 mA
I_{GES}	$V_{CE} = 0V$, $V_{GE} = \pm 20V$			± 400 nA
$V_{CE(sat)}$	$I_C = 100A$, $V_{GE} = 15V$, Note 1 $I_C = 400A$	1.25	1.50	V
		1.80		V

Symbol	Test Conditions ($T_J = 25^\circ\text{C}$, Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
g_{fs}	$I_C = 60\text{A}, V_{CE} = 10\text{V}$, Note 1	85	140	S
C_{ies}	$V_{CE} = 25\text{V}, V_{GE} = 0\text{V}, f = 1\text{MHz}$		31	nF
C_{oes}			1560	pF
C_{res}			68	pF
Q_g	$I_C = 100\text{A}, V_{GE} = 15\text{V}, V_{CE} = 0.5 \cdot V_{CES}$		900	nC
Q_{ge}			140	nC
Q_{gc}			300	nC
$t_{d(on)}$	Inductive Load, $T_J = 25^\circ\text{C}$ $I_C = 100\text{A}, V_{GE} = 15\text{V}$ $V_{CE} = 480\text{V}, R_G = 1\Omega$		50	ns
t_{ri}			50	ns
E_{on}			2.95	mJ
$t_{d(off)}$			220	ns
t_{fi}			125	200 ns
E_{off}			2.30	4.40 mJ
$t_{d(on)}$	Inductive Load, $T_J = 125^\circ\text{C}$ $I_C = 100\text{A}, V_{GE} = 15\text{V}$ $V_{CE} = 480\text{V}, R_G = 1\Omega$		50	ns
t_{ri}			50	ns
E_{on}			4.40	mJ
$t_{d(off)}$			295	ns
t_{fi}			225	ns
E_{off}			4.25	mJ
R_{thJC}		0.05	0.125 °C/W	
R_{thCS}				°C/W

SOT-227B miniBLOC (IXGN)



SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	1.240	1.255	31.50	31.88
B	.307	.323	7.80	8.20
C	.161	.169	4.09	4.29
D	.161	.169	4.09	4.29
E	.161	.169	4.09	4.29
F	.587	.595	14.91	15.11
G	1.186	1.193	30.12	30.30
H	1.496	1.505	38.00	38.23
J	.460	.481	11.68	12.22
K	.351	.378	8.92	9.60
L	.030	.033	0.76	0.84
M	.496	.506	12.60	12.85
N	.990	1.001	25.15	25.42
O	.078	.084	1.98	2.13
P	.195	.235	4.95	5.97
Q	1.045	1.059	26.54	26.90
R	.155	.174	3.94	4.42
S	.186	.191	4.72	4.85
T	.968	.987	24.59	25.07
U	-.002	.004	-0.05	0.1

Note 1. Pulse test, $t \leq 300\mu\text{s}$; duty cycle, $d \leq 2\%$.

IXYS Reserves the Right to Change Limits, Test Conditions, and Dimensions.

IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents:	4,835,592	4,931,844	5,049,961	5,237,481	6,162,665	6,404,065 B1	6,683,344	6,727,585	7,005,734 B2	7,157,338B2
	4,860,072	5,017,508	5,063,307	5,381,025	6,259,123 B1	6,534,343	6,710,405 B2	6,759,692	7,063,975 B2	
	4,881,106	5,034,796	5,187,117	5,486,715	6,306,728 B1	6,583,505	6,710,463	6,771,478 B2	7,071,537	

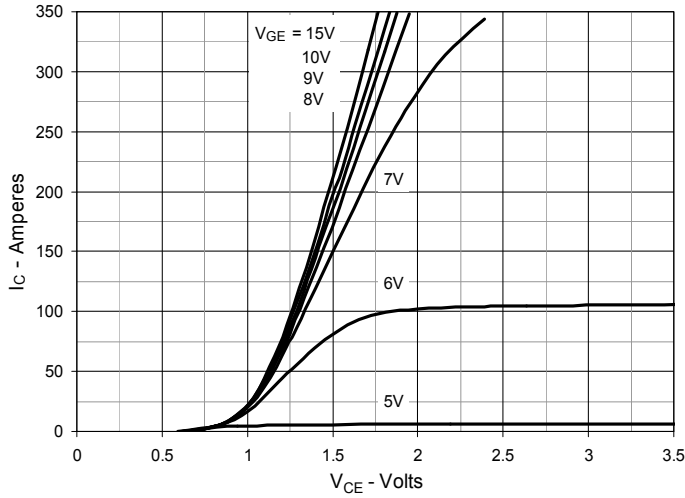
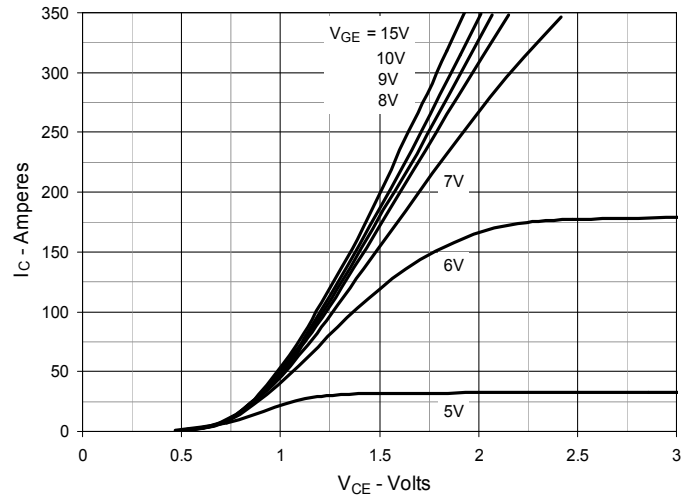
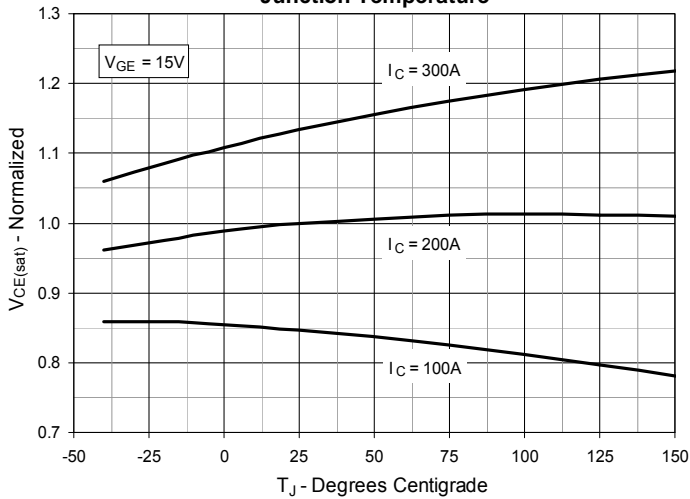
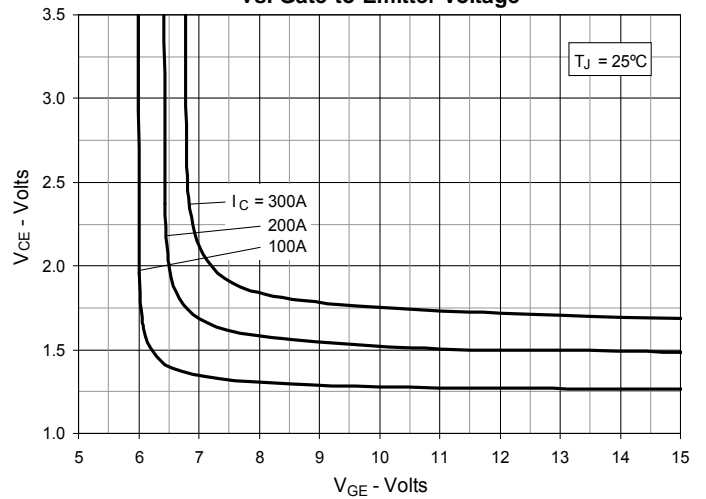
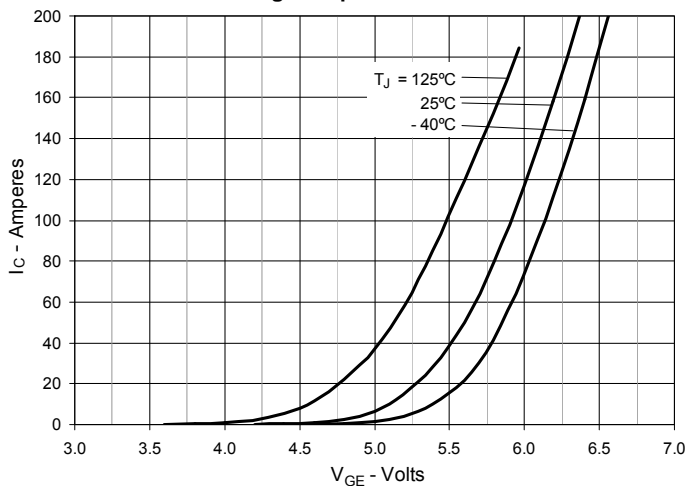
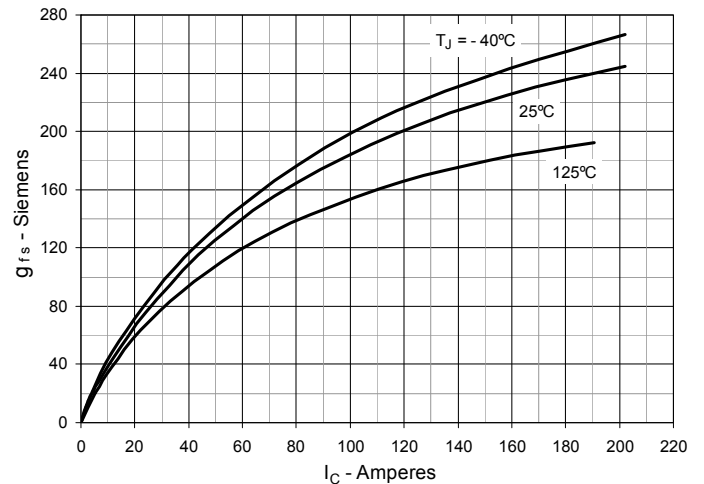
Fig. 1. Output Characteristics @ $T_J = 25^\circ\text{C}$

Fig. 2. Output Characteristics @ $T_J = 125^\circ\text{C}$

Fig. 3. Dependence of $V_{CE(sat)}$ on Junction Temperature

Fig. 4. Collector-to-Emitter Voltage vs. Gate-to-Emitter Voltage

Fig. 5. Input Admittance

Fig. 6. Transconductance


Fig. 7. Gate Charge

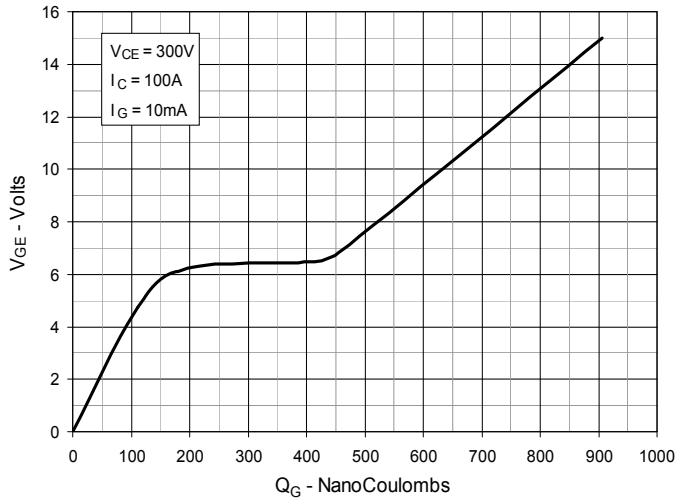


Fig. 8. Capacitance

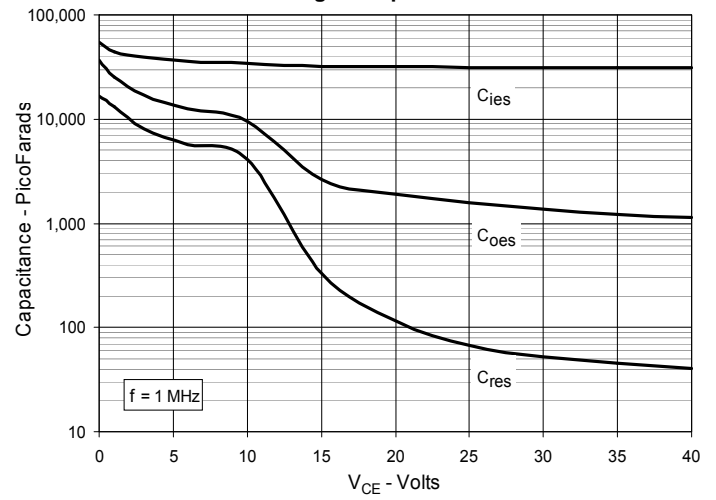


Fig. 10. Reverse-Bias Safe Operating Area

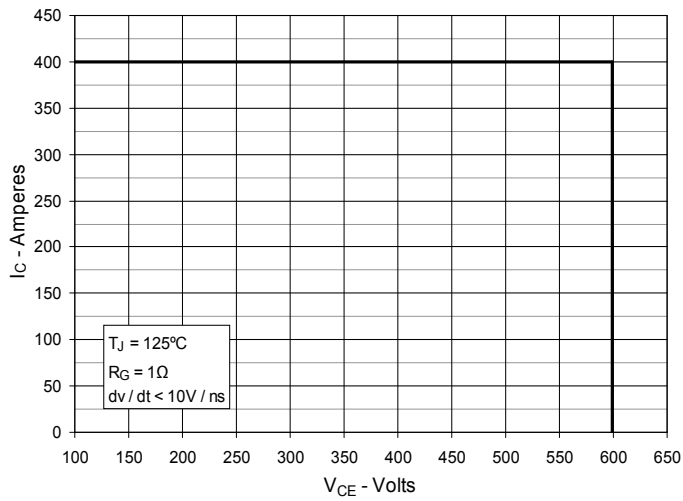
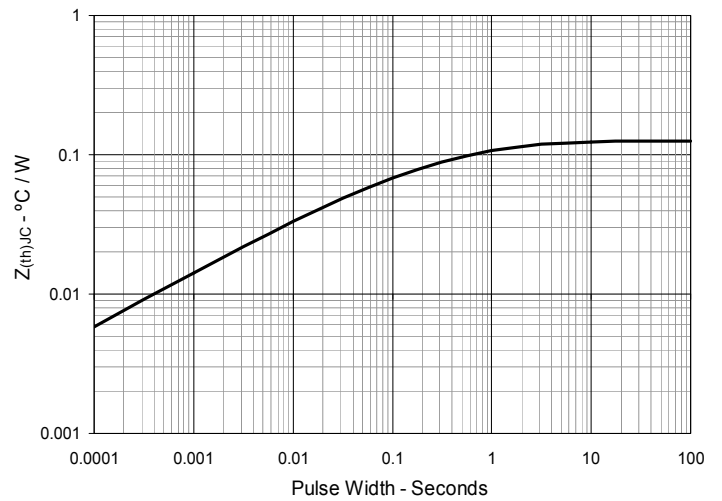


Fig. 11. Maximum Transient Thermal Impedance



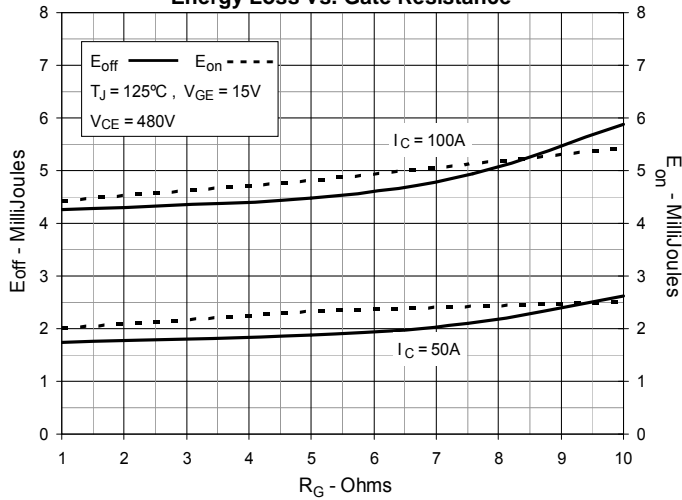
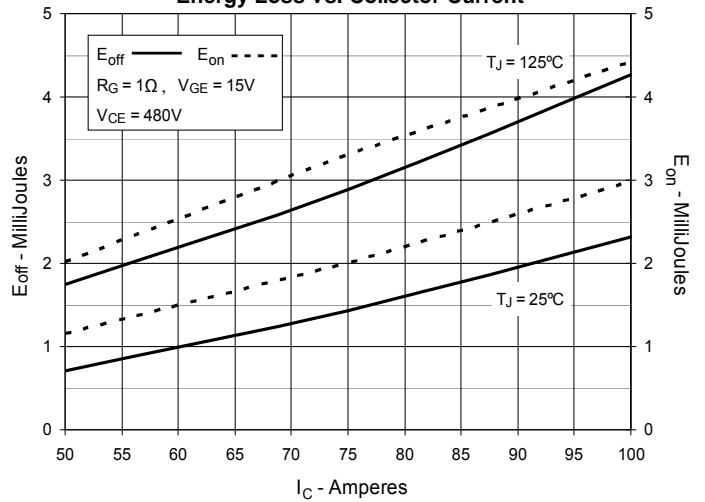
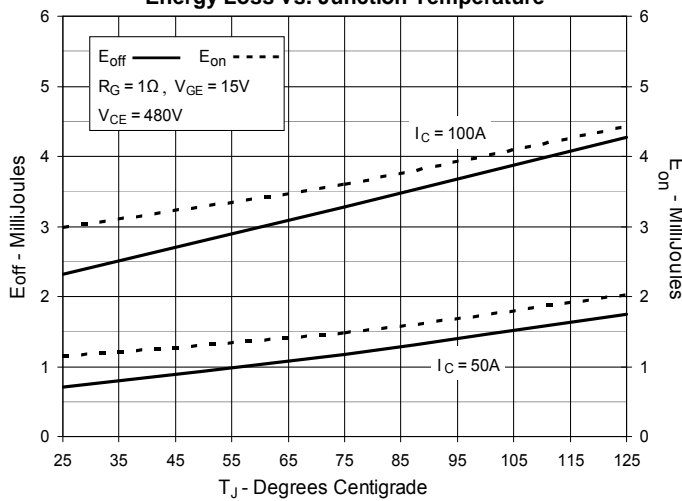
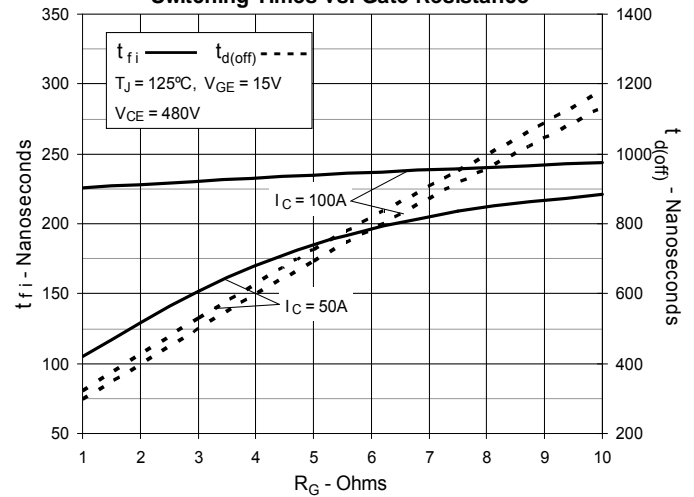
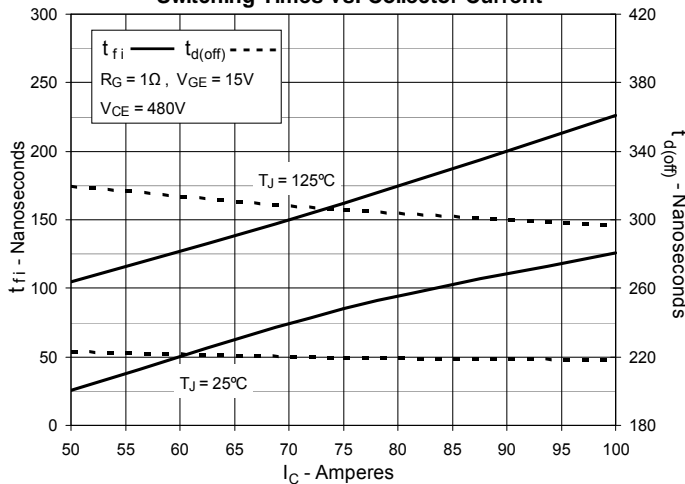
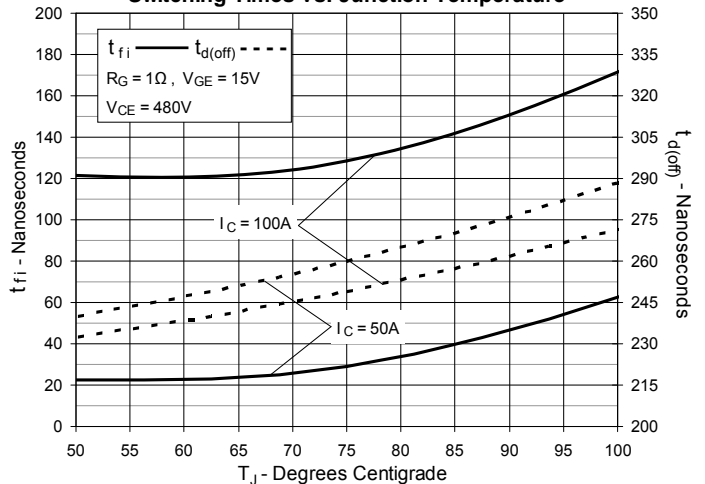
**Fig. 12. Inductive Switching
Energy Loss vs. Gate Resistance**

**Fig. 13. Inductive Switching
Energy Loss vs. Collector Current**

**Fig. 14. Inductive Switching
Energy Loss vs. Junction Temperature**

**Fig. 15. Inductive Turn-off
Switching Times vs. Gate Resistance**

**Fig. 16. Inductive Turn-off
Switching Times vs. Collector Current**

**Fig. 17. Inductive Turn-off
Switching Times vs. Junction Temperature**


Fig. 18. Inductive Turn-on
Switching Times vs. Gate Resistance

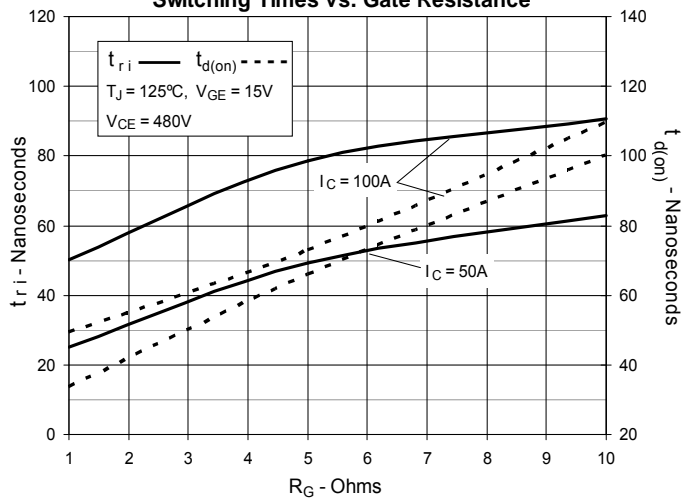


Fig. 19. Inductive Turn-on
Switching Times vs. Collector Current

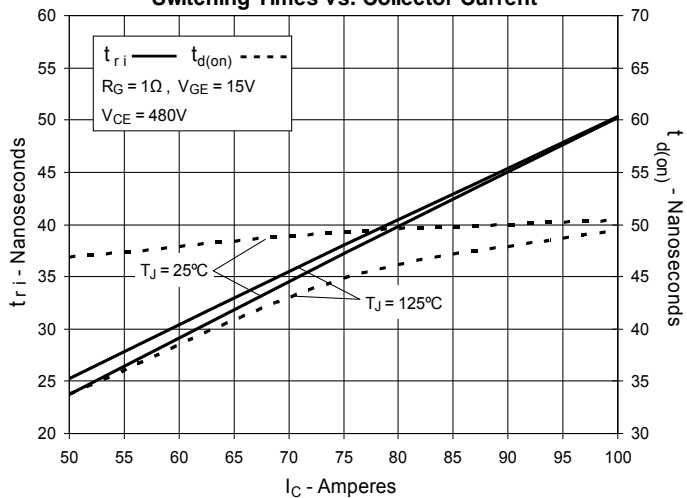
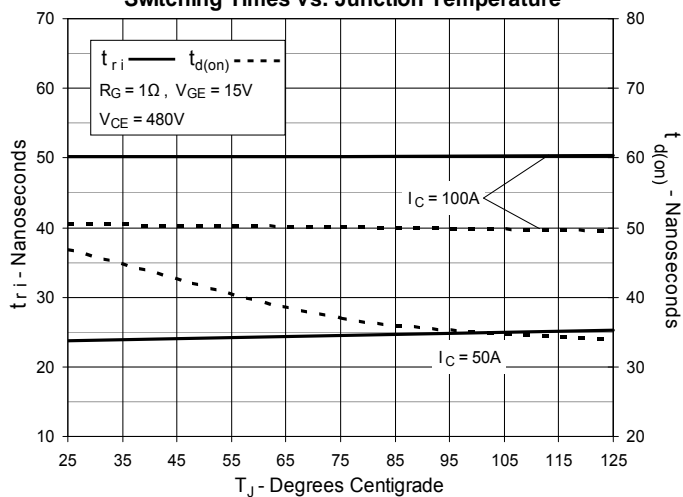


Fig. 20. Inductive Turn-on
Switching Times vs. Junction Temperature





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